





(1.27 mm) .050"

CLP SERIES

PROFILE DUAL WIPE SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?CLP

Insulator Material:

Black Liquid Crystal Polymer Contact Material:

Phosphor Bronze

Plating: Sn or Au over 50 μ" (1.27 μm) Ni

Current Rating (CLP/FTSH): 3.3 A per pin

(1 pin powered per row) Voltage Rating: 240 VAC/340 VDC

Operating Temp Range:

55 °C to +125 °C Contact Resistance: $10~\text{m}\Omega$

Insertion Depth:

Top Entry = (1.40 mm) .055" minimum, Bottom Entry = (2.41 mm) .095" minimum plus board thickness DH Entry = (2.31 mm) .091" to (2.67 mm) .105" Normal Force:

60 grams (0.59 N) average Max Cycles:

100 with 10 μ" (0.25 μm) Au RoHS Compliant:

PROCESSING

Lead-Free Solderable:

SMT Lead Coplanarity: (0.10 mm) .004" max (02-35) (0.15 mm) .006" max (36-50)

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



ALSO AVAILABLE (MOQ Required)

- · Single row
- · Other platings

Contact Samtec.





